

Description

Features

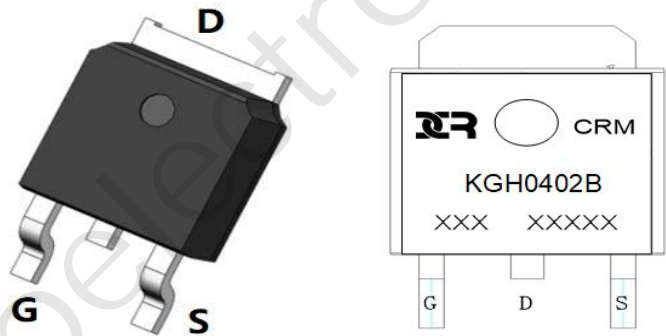
- 40V, 140A
 $R_{DS(ON)}$ Typ = 2.3mΩ @ $V_{GS} = 10V$
- Advanced Split Gate Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- 100% UIS TESTED!
- 100% ΔV_{ds} TESTED!



Schematic Diagram

Application

- Load Switch
- PWM Application
- Power Management



Marking and Pin Assignment

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMKGH0402B	CRMKGH0402B	TO-252-3L	TAPING	13"	2500	25000

Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	40	V	
V _{GS}	Gate-to-Source Voltage	±20	V	
I _D	Continuous Drain Current	T _C = 25°C	140	A
		T _C = 100°C	84	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	560	A	
E _{AS}	Single Pulsed Avalanche Energy ⁽²⁾	272	mJ	
P _D	Power Dissipation	T _C = 25°C	100	W
R _{θJC}	Thermal Resistance, Junction to Case	1.25	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 40V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	2.4	2.9	3.6	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 30A	-	2.3	3	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 20V, f = 1MHz	-	2803	-	pF
C _{oss}	Output Capacitance		-	948	-	pF
C _{rss}	Reverse Transfer Capacitance		-	70	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 20V, I _D = 20A	-	45	-	nC
Q _{gs}	Gate Source Charge		-	9.8	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	8.5	-	nC

Switching Characteristics

t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 20V I _D = 20A, R _{GEN} = 3Ω	-	16	-	ns
t _r	Turn-On Rise Time		-	25.5	-	ns
t _{d(off)}	Turn-Off DelayTime		-	32	-	ns
t _f	Turn-Off Fall Time		-	12	-	ns

Drain-Source Diode Characteristics and Max Ratings

I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 30A	-	-	140	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	560	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time		-	40	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	35	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting T_J=25°C, V_{DD}=20V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=33A
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

Test Circuit



Figure 1: Gate Charge Test Circuit & Waveform



Figure 2: Resistive Switching Test Circuit & Waveform

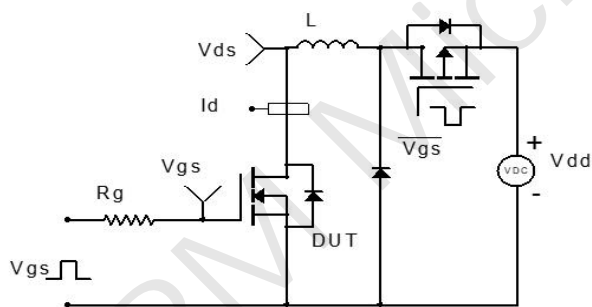
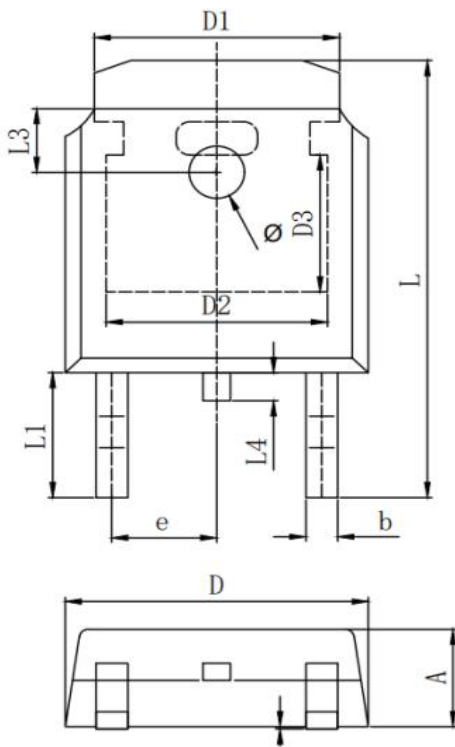


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform



Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(TO-252-3L)




SYMBOL	MILLIMETER		
	MIN	Typ.	MAX
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c (电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
θ 1	9° TYP		
θ 2	9° TYP		

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